High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology

DESCRIPTION

As part of the SurfLight™ portfolio, the VSMY2853 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- Automotive sensors
- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination

FEATURES

- Package type: surface-mount
- Package form: side view
- Dimensions (L x W x H in mm): 2.3 x 2.55 x 2.3
- AEC-Q101 qualified
- Peak wavelength: λ_p = 850 nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity: φ = ± 28°
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2xx3SLX01 and VEMR2xx3SLX01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

Pb-free

e3

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr)	φ (°)	λ_p (nm)	t_r (ns)
VSMY2853SLX01	50	± 28	850	10

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2853SLX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	t_p/T = 0.5, t_p = 100 µs	I_{FM}	200	mA
Surge forward current	t_p = 100 µs	I_{FSM}	1	A
Power dissipation		P_V	190	mW
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	-40 to +85	°C
Storage temperature range		T_{stg}	-40 to +100	°C
Soldering temperature	According to Fig. 7, J-STD-020	T_{sd}	260	°C
Thermal resistance junction to ambient	EIA / JESD51	R_{thJA}	250	K/W

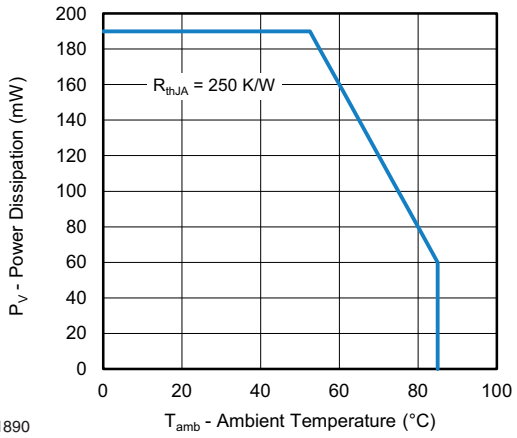


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

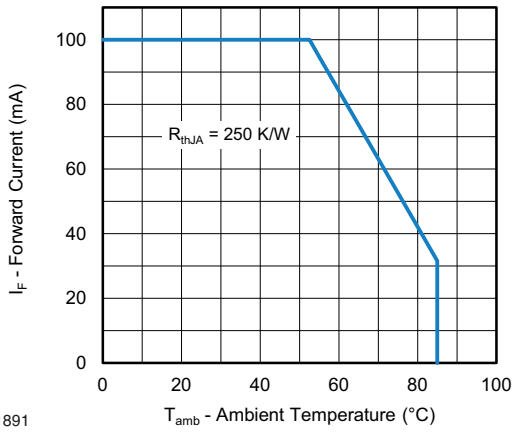


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 100 mA, t_p = 20 ms	V_F	-	1.6	1.9	V
	I_F = 1 A, t_p = 100 µs	V_F	-	2.8	-	V
Temperature coefficient of V_F	I_F = 100 mA	TK_{VF}	-	-1.5	-	mV/K
Reverse current		I_R	Not designed for reverse operation			µA
Junction capacitance	V_R = 0 V, f = 1 MHz, E = 0 mW/cm²	C_J	-	50	-	pF
Radiant intensity	I_F = 100 mA, t_p = 20 ms	I_e	27	50	75	mW/sr
	I_F = 1 A, t_p = 100 µs	I_e	-	350	-	mW/sr
Radiant power	I_F = 100 mA, t_p = 20 ms	ϕ_e	-	55	-	mW
Temperature coefficient of radiant power	I_F = 100 mA	$TK\phi_e$	-	-0.12	-	%/K
Angle of half intensity		φ	-	± 28	-	°
Peak wavelength	I_F = 100 mA	λ_p	840	850	870	nm
Spectral bandwidth	I_F = 100 mA	$\Delta\lambda$	-	30	-	nm
Temperature coefficient of λ_p	I_F = 100 mA	$TK\lambda_p$	-	0.25	-	nm/K
Rise time	I_F = 100 mA, 10 % to 90 %	t_r	-	10	-	ns
Fall time	I_F = 100 mA, 10 % to 90 %	t_f	-	10	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

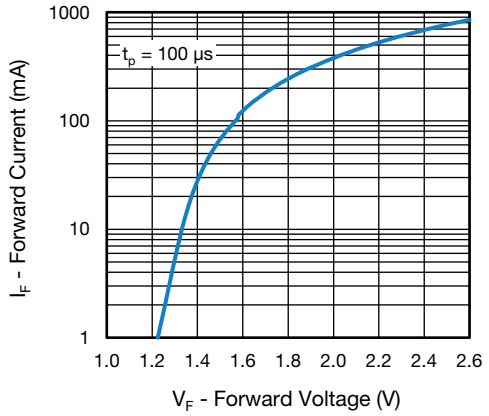


Fig. 3 - Forward Current vs. Forward Voltage

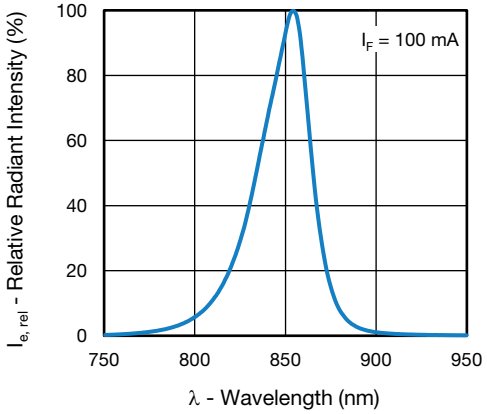


Fig. 5 - Relative Radiant Power vs. Wavelength

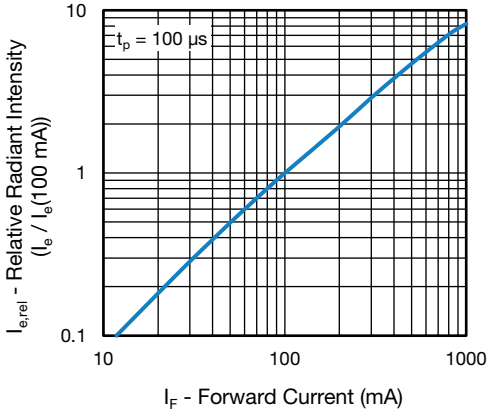


Fig. 4 - Relative Radiant vs. Forward Current

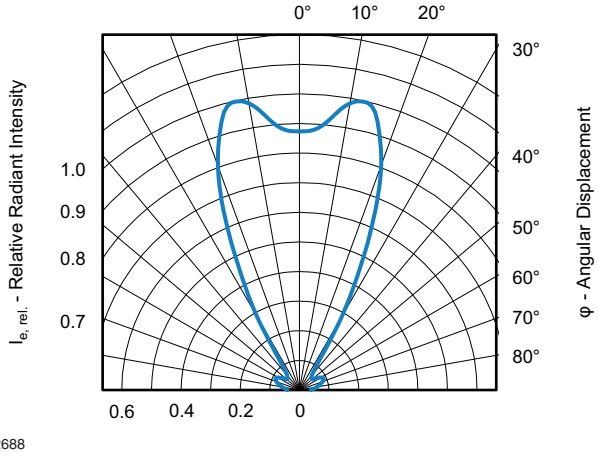


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

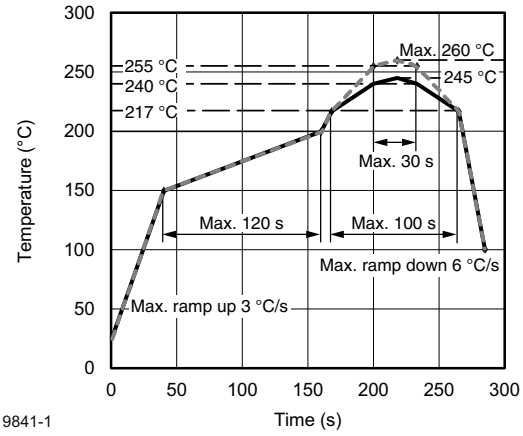


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

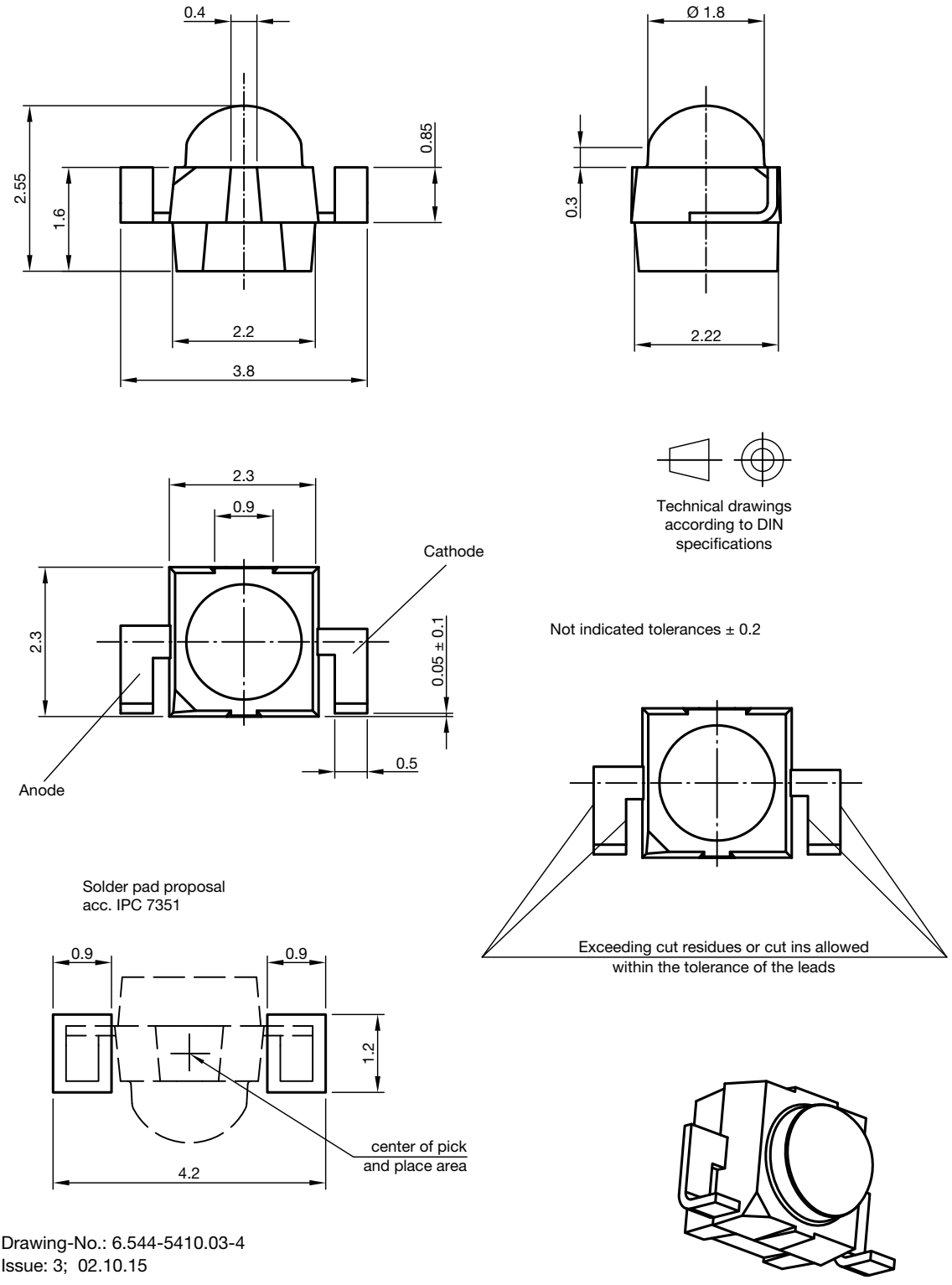
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, according to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENSIONS in millimeters: **VSMY2853SLX01**



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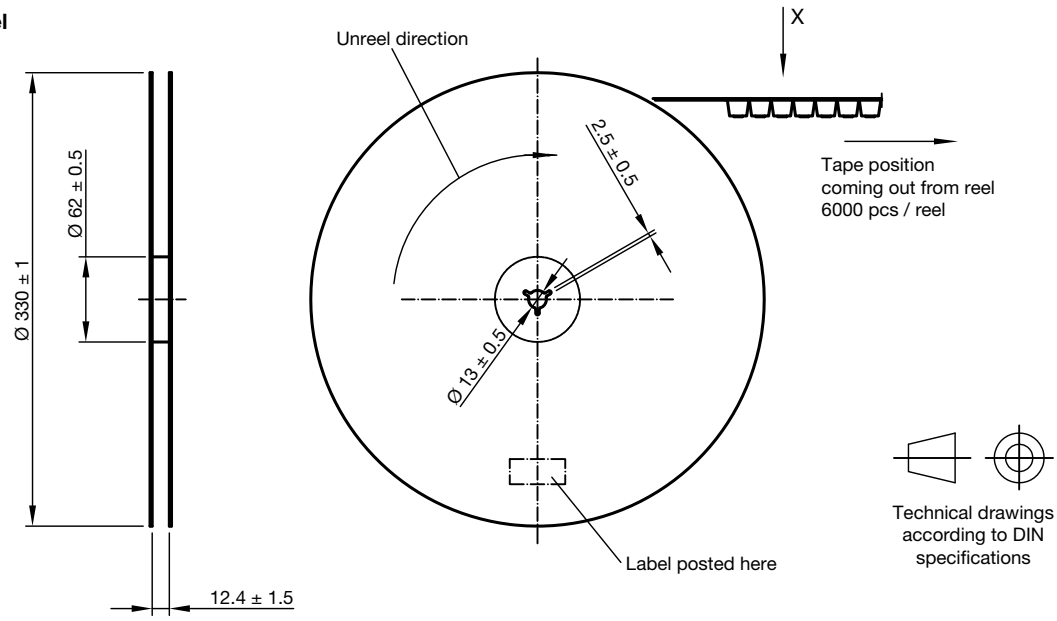
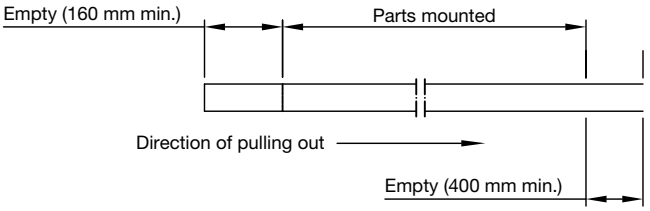
Issue: 3; 02.10.15

TAPING AND REEL DIMENSIONS in millimeters: **VSMY2853SLX01**

Reel

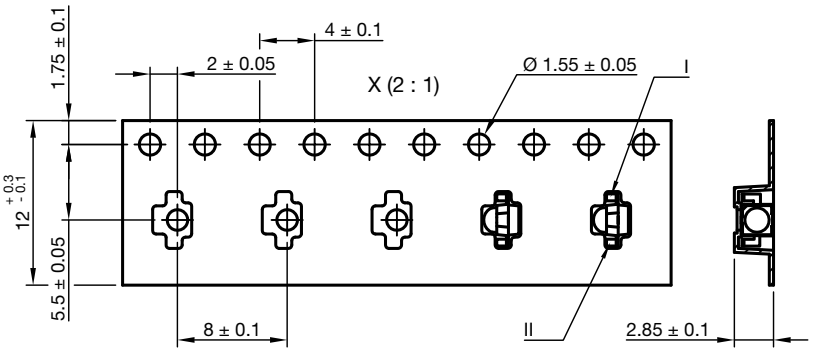


Leader and trailer tape



Terminal position in tape

Device	Lead I	Lead II
VSMB2943SLX01	Cathode	Anode
VSMF2893SLX01		
VSMB2948SL		
VEMD2023SLX01		
VEMD2523SLX01		
VEMT2023SLX01	Collector	Emitter
VEMT2523SLX01		
VSMY2853SL	Anode	Cathode
VSMY2943SL		
VSMY294310SL		



Drawing-No.: 9.800-5123.01-4
Issue: 4; 02.10.15

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